

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Kosaku Hioki</td> <td>08/22/2013</td> </tr> <tr> <td>Kazumasa Takai</td> <td>08/22/2013</td> </tr> <tr> <td>Takeshi Naganuma</td> <td>08/22/2013</td> </tr> <tr> <td>Yoshihiro Niwa</td> <td>08/22/2013</td> </tr> </tbody> </table>		Name	Execution Date	Kosaku Hioki	08/22/2013	Kazumasa Takai	08/22/2013	Takeshi Naganuma	08/22/2013	Yoshihiro Niwa	08/22/2013
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RECEIVING PARTY DATA											
Name:	Semiconductor Components Industries, LLC										
Street Address:	5005 E. McDowell Rd.										
Internal Address:	A700										
City:	Phoenix										
State/Country:	ARIZONA										
Postal Code:	85008										
PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13952479</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13952479						
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Application Number:	13952479										
CORRESPONDENCE DATA											
Fax Number:	6022443169										
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>											
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ATTORNEY DOCKET NUMBER:	299803808C01										
NAME OF SUBMITTER:	Becky Newnam										
Signature:	/Becky Newnam/										

CH \$40.00 13952479

Date:

08/23/2013

Total Attachments: 2

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ASSIGNMENT & AGREEMENT

200803808C01

For good and valuable consideration, the receipt of which is hereby acknowledged, we,

Name	of (City/State/Country)
Kosaku Hioki	Gifu, Japan
Kazumasa Takai	Gifu, Japan
Takeshi Naganuma	Aichi, Japan
Yoshihiro Niwa	Gifu, Japan

have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto Semiconductor Components Industries, LLC (SCI), a limited liability Company of the State of Delaware, having its principal office in Phoenix, State of Arizona, United States of America, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain inventions relating to improvements in

DRIVER CIRCUIT AND METHOD

Attorney Docket No. 200803808C01

described, illustrated, and claimed in an application for Letters Patent of the United States of America executed by us, together with the entire right, title and interest in and to the application, and in and to Letters Patent which may be issued upon the application, and upon any division, extension, continuation, or reissue thereof.

We hereby also sell, assign, and transfer unto SCI, the entire right, title, and interest in and to the invention and in and to applications for Letters Patent therefor in all countries foreign to the United States of America, including all rights under any and all international conventions and treaties in respect of the inventions and the applications for Letters Patent in foreign countries, and we further authorize SCI to apply for Letters Patent in foreign countries directly in its own name, and to claim the priority of the filing date of the application for Letters Patent of the United States of America under the provisions of any and all international conventions and treaties.

We hereby authorize and request the Commissioner of Patents and Trademarks of the United States of America to issue Letters Patent upon the aforesaid application, division, extension, continuation, or reissue, to SCI, for the sole use and behalf of SCI, its successors, assigns, and legal representatives, to the full end of the term for which the Letters Patent may be granted, the same as they would have been held and enjoyed by us had this assignment not been made, and we hereby authorize and request the equivalent authorities in foreign countries to issue the patents of their respective countries to SCI.

We agree that, when requested, we will, without charge to SCI, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the inventions in any and all countries and for vesting title thereto in SCI, its successors, assigns, and legal representatives or nominees.

We covenant with SCI, its successors, assigns, and legal representatives, that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.

By (Inventor signature): Kosaku Hioki
Kosaku Hioki

Witnessed by (Witness signature): Yasunori Nagata

Printed name of Witness: Yasunori Nagata

Signed and Witnessed on (date): August 22, 2013

By (Inventor signature): Kazumasa Takai
Kazumasa Takai

Witnessed by (Witness signature): Yasunori Nagata

Printed name of Witness: Yasunori Nagata

Signed and Witnessed on (date): August 22, 2013

By (Inventor signature): Takeshi Naganuma
Takeshi Naganuma

Witnessed by (Witness signature): Yasunori Nagata

Printed name of Witness: Yasunori Nagata

Signed and Witnessed on (date): August 22, 2013

By (Inventor signature): Yoshihiro Niwa
Yoshihiro Niwa

Witnessed by (Witness signature): Yasunori Nagata

Printed name of Witness: Yasunori Nagata

Signed and Witnessed on (date): August 22, 2013